Hybrid 8j247 Traveler

February 23, 2000

1 Connectivity

Repairs on shorts:

Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 8J247 has die: 143-045 143-046 143-069 143-048 176-041 176-044 176-045 176-049

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 8j247 classification info. Created 09:06:09 02/23/00

Hybrid 8j247 quality: fair
Chip classification: good fair fair good good good fair fair
Bad channels (chip-channel): 1-46 2-118
Bad cells: none
Random bad capacitors (chip-cell-channel): 6-27-104 6-35-76 6-41-112
   6-42-19 6-44-3 7-1-107 7-22-69 7-24-73 7-45-108
Channels at pedestal needed for DCMS: 31.6 29.8 31.6 31.6 32.6 32.7 33.6 32.6
```

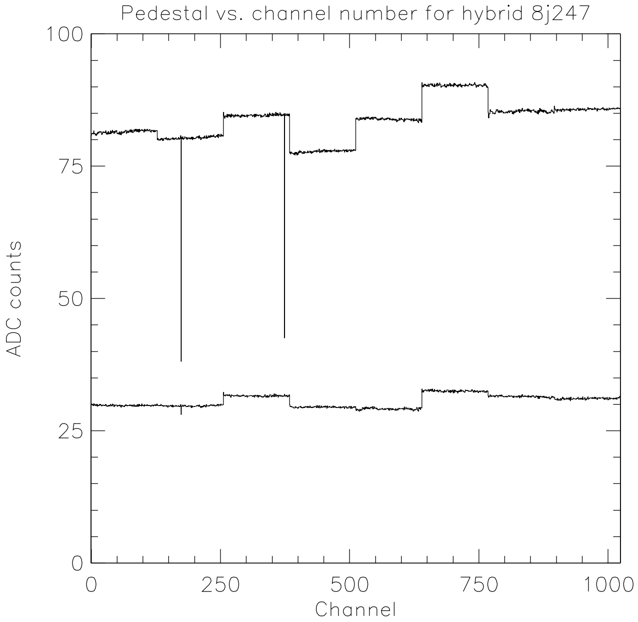
4 Comments

Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

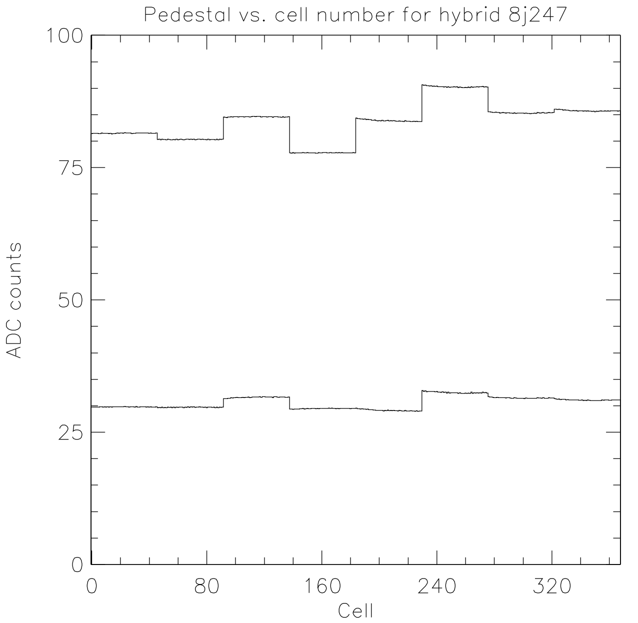
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

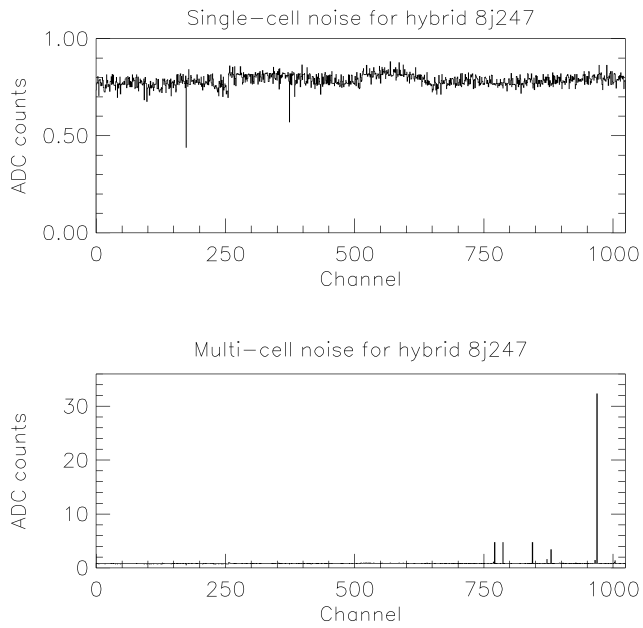
Pedestal vs. Pipeline Cell ID



6 Noise

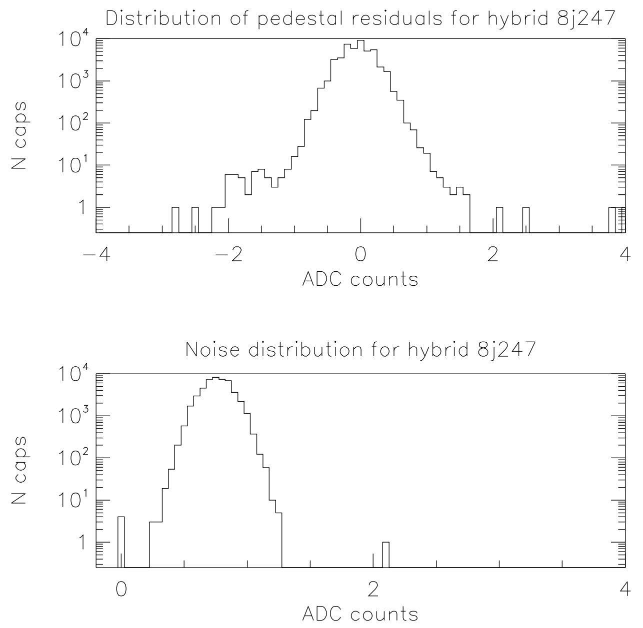
The following plots show the single-cell and multi-cell RMS noise:

RMS Noise



The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise



7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in